# HYBRID INTEGRATED CIRCUIT VHF/UHF WIDE-BAND AMPLIFIER

Three-stage wide-band amplifier in hybrid integrated circuit technique on a thin-film substrate, intended for use in mast-head booster-amplifiers, as an amplifier in MATV and CATV systems, and as general-purpose amplifier for v.h.f. and u.h.f. applications.

# QUICK REFERENCE DATA

Frequency range	f		40 to 860	MHz
Source and load (characteristic) impedance	$R_s = R_{\ell} = Z_0$	-	75	Ω
Transducer gain	G <sub>tr</sub> =   s <sub>f</sub>   <sup>2</sup>	typ.	28	dΒ
Flatness of frequency response	±Δ s <sub>f</sub>   <sup>2</sup>	typ.	1	фB
Output voltage at -60 dB intermodulation distortion (DIN 45004, 3-tone) VHF UHF	V <sub>o(rms)</sub> V <sub>o(rms)</sub>	typ.		d8⊭V d8⊭V
Noise figure	F	typ.	7	dB
D.C. supply voltage	V <sub>B</sub>	-	12	V ± 10%
Operating ambient temperature	T <sub>amb</sub>	-20 to +70		°C

ENCAPSULATION 9-pin, in-line, resin-coated body, see MECHANICAL DATA (Fig.2)

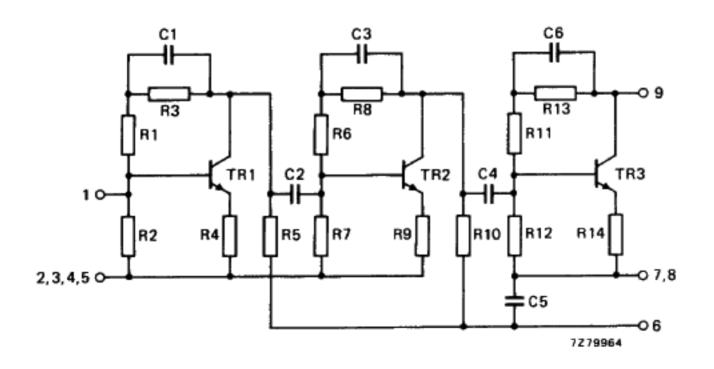


Fig. 1 Circuit diagram.

RATINGS						
Limiting values in accor	rdance with the Abso	lute Maximum	System (IEC 13	4)		
Operating ambient tem	perature		T <sub>amb</sub>	-20 to +70		oC
Storage temperature			T <sub>stg</sub>	-40 to +125		°C
D.C. supply voltage			V <sub>B</sub>	max.	15	٧
Peak incident powers o	n pins 1 and 8		P <sub>I1M</sub> , P <sub>I8M</sub>	max.	100	mW
CHARACTERISTICS						
Measuring conditions						_
Ambient temperature			T <sub>amb</sub>	=	25	οС
D.C. supply voltage			V <sub>B</sub>	Ξ	12	٧
Source impedance and	load impedance		R <sub>s</sub> , R <sub>ℓ</sub>	=	75	$\Omega$
Characteristic impedan	ce of h.f. connections	;	z <sub>o</sub>	=	75	$\Omega$
Frequency range			f	=	40 to 860	MHz
Performance						
Supply current			I <sub>В</sub>	typ.	100	mΑ
Transducer gain			G <sub>tr</sub> =  s <sub>f</sub> ( 2	typ.	28 26 to 31	dB dB
Flatness of frequency r	esponse		±∆ s4[²	typ.	1	dB
Individual maximum v.	s.w.r.					
input			vswr <sub>(i)</sub>	typ,	2,3	•
output			vswr <sub>(a)</sub>	typ.	1,9	*
Back attenuation						
f = 100 MHz			s <sub>r</sub>   <sup>2</sup>   s <sub>r</sub>   <sup>2</sup>	typ.		dB dB
f = 860 MHz			l srl	typ.	35	uь
Output voltage at -60 dB intermod (DIN 45004, par. 6,3						
VHF			Vo(rms)	> typ.		dBμV dBμV
UHF			V <sub>o(rms)</sub>	> typ.		dΒμV dΒμV
Noise figure			F	typ.	7	dB
	s-parameters:	s <sub>f</sub> = s <sub>21</sub>	s <sub>i</sub> = s <sub>11</sub>			
		s <sub>r</sub> = \$12	\$0 = \$22			
		1 12	0 22			

Highest value, for a sample, occurring in the frequency range.

Dimensions in mm

#### **OPERATING CONDITIONS**

Ambient temperature range	T <sub>amb</sub> –20 to +70 <sup>o</sup> C	
D.C. supply voltage	$V_B = 12 V \pm 10$	%
Frequency range	f 40 to 860 MHz	
Source impedance and load impedance	$R_{\rm a}$ , $R_{\rm o}$ = 75 $\Omega$	

#### **MECHANICAL DATA**

The device is resin coated.

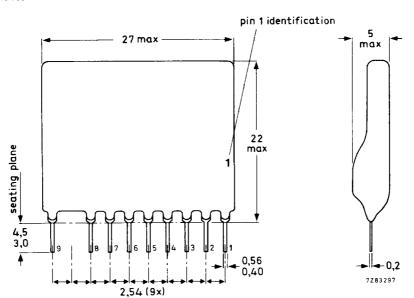


Fig. 2 Encapsulation.

#### Terminal connections

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1 = input
2,3,4,5 and 7,8 = common
6 = supply (+)
9 = output/supply (+)
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# Soldering recommendations

#### Hand soldering

Maximum contact time for a soldering-iron temperature of 260  $^{\rm O}{\rm C}$  up to the seating plane is 5 s.

### Dip or wave soldering

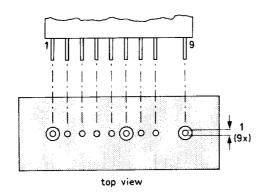
260 °C is the maximum permissible temperature of the solder; it must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds. The device may be mounted against the printed-circuit board, but the temperature of the device must not exceed 125 °C. If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature below the allowable limit.

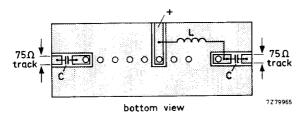
# Mounting recommendations

The module should preferably be mounted on double-sided printed-circuit board, see the example shown below.

Input and output should be connected to 75  $\Omega$  tracks.

The connections to the 'common' pins should be as close to the seating plane as possible.





L > 5  $\mu$ H; e.g. catalogue no. 3122 108 20150 or 27 turns enamelled Cu wire (0,3 mm) wound on a ferrite core (material 4B1; catalogue no. 3122 104 91110) with a diameter of 1,6 mm. C > 220 pF ceramic capacitor.

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Fig. 3 Printed-circuit board holes and tracks.

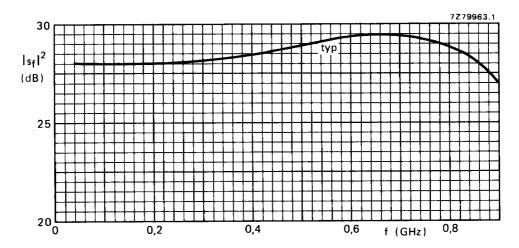


Fig. 4 Transducer gain as a function of frequency;  $Z_0 = 75 \Omega$ .

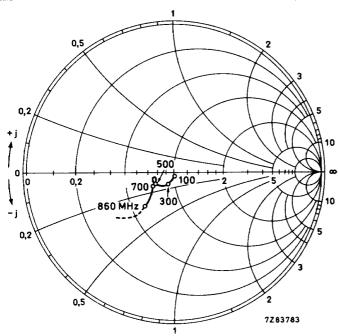


Fig. 5 Input impedance derived from input reflection coefficient  $s_i$ , co-ordinates in ohm x 75; typical values.

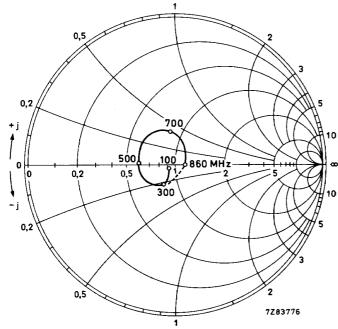


Fig. 6 Output impedance derived from output reflection coefficient s<sub>0</sub>, co-ordinates in ohm x 75; typical values.

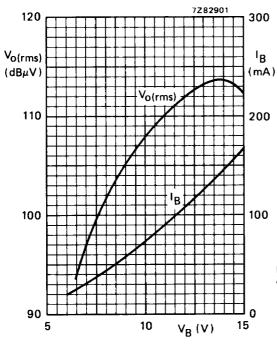


Fig. 7 Output voltage and supply current as a function of the supply voltage; typical values.

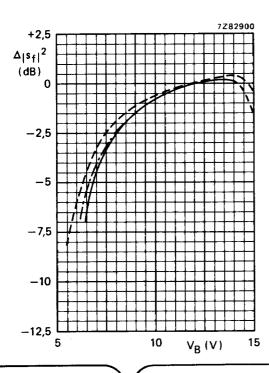


Fig. 8 Variation of transducer gain with supply voltage; reference 0 dB at 12 V;

- f = 500 MHz;

-- f = 100 MHz; ---- f = 860 MHz;

typical values.